



**ENGINEERING & MANAGEMENT EXAMINATIONS, JUNE - 2007**  
**MICROELECTRONICS & OPTOELECTRONIC DEVICES**  
**SEMESTER - 4**

Time : 3 Hours ]

[ Full Marks : 70

**GROUP - A**

**( Multiple Choice Type Questions )**

1. Choose the correct alternatives for the following : 10 × 1 = 10
- i) Bulk Micromachining makes Micromechanical devices by etching deeply into
- |                    |                   |                          |
|--------------------|-------------------|--------------------------|
| a) Germanium Wafer | b) Carbon Wafer   |                          |
| c) Silicon Wafer   | d) Gallium Wafer. | <input type="checkbox"/> |
- ii) In *P-I-N* Diode the *I* part refers to
- |                            |                             |                          |
|----------------------------|-----------------------------|--------------------------|
| a) extrinsic substrate     | b) intrinsic substrate      |                          |
| c) intrinsic semiconductor | d) extrinsic semiconductor. | <input type="checkbox"/> |
- iii) Electron Affinity depends on
- |                                |  |                          |
|--------------------------------|--|--------------------------|
| a) semiconductor material      |  |                          |
| b) doping of the semiconductor |  |                          |
| c) applied potential           |  |                          |
| d) none of these.              |  | <input type="checkbox"/> |
- iv) In photodiode, the light energy
- |  |  |                          |
|--|--|--------------------------|
| a) is converted to electrical energy     |  |                          |
| b) is converted to mechanical energy     |  |                          |
| c) is converted to sound energy          |  |                          |
| d) is not converted into any other form. |  | <input type="checkbox"/> |



**GROUP - B****( Short Answer Type Questions )**Answer any *three* of the following.

3 × 5 = 15

2. Derive the one-dimensional continuity equation for minority carriers in generation-recombination process, under low injection condition.  $G_n$ ,  $G_p$ ,  $R_n$  and  $R_p$  are generation and recombination rates for electron / hole. 5
3. What is population inversion in Laser ? What is external quantum efficiency in a semiconductor Laser ? What is the optical feedback & Laser oscillation by which the amplified coherent emission is obtained ? 1 + 2 + 2
4. An n-type semiconductor at thermal equilibrium (  $T = 300$  K ) has a linear variation in doping concentration given by  $N_d(x) = 10^{16} - 10^{19}x$ ,  $0 \leq x \leq 1 \mu\text{m}$ .  
Determine induced electric field. ( Volt equivalent temperature at room temperature = 0.02V ) 5
5. Discuss the principle of operation of vertical power BJT. 5
6. With energy band diagram describe Schottky junction barrier formation. Describe its operation under external bias. 2 + 3

**GROUP - C****( Long Answer Type Questions )**Answer any *three* questions of the following.

3 × 15 = 45

7. a) What is SCR ? Point out its major uses.
- b) By using two-transistor analogy, briefly describe the basic operation of two-terminal SCR.
- c) Is it possible to observe the purpose of SCR by connecting two separate transistors ? Explain.
- d) How does the presence of third terminal control the I-V response of SCR ? Explain with system diagram. 2 + 6 + 2 + 5



8. a) Sketch the ideal energy band diagram of a metal-semiconductor junction in which  $\Phi_m < \Phi_s$ . Explain why this is an Ohmic contact.
- b) Discuss how 2D-electron gas is formed in semiconductor heterojunction.
- c) The Schottky barrier height of a Si Schottky junction is  $\Phi_{BN} = 0.59V$ , the effective Richardson constant is  $A^* = 111 \text{ A/K}^2\text{-cm}^2$  and the cross-sectional area is  $a = 10^{-4} \text{ cm}^2$ .

For  $T = 100 \text{ K}$ , calculate

- i) Ideal reverse saturation current
- ii) The diode current for  $V$  ( applied ) = 0.30 V. ( 5 + 2 ) + 3 + 5

9. a) Illustrate the basic process flow in micromachining ? What do you mean by optical lithography ?
- b) What do you mean by plasma etching ?
- c) Explain one non-lithographic micro-fabrication technology. ( 6 + 3 ) + 2 + 4

10. a) What is the advantage of optical fibre over the copper wire system ?
- b) What is the difference between step index and graded index fibres ?
- c) Distinguish between non-radiative & radiative recombination processes in a semiconductor. Express the internal quantum efficiency in terms of the life times of the processes.
- d) A silica optical fibre has a core refractive index of 1.5 and the cladding refractive index of 1.450. Calculate
- i) the critical angle for the core cladding interface.
- ii) the acceptance angle in air for the fibre.
- iii) the Numerical aperture ( NA ) of the fibre. 3 + 1 + ( 2 + 3 ) + ( 3 × 2 )

11. Write short notes on any *three* of the following : 3 × 5

- a) Solar cell
- b) Semiconductor laser
- c) Insulated bipolar junction transistor
- d) P-I-N photodiode
- e) O.E.I.C.